

**ZXTP4003Z**

**100V PNP LED DRIVING TRANSISTOR IN SOT89**

**Features**

- $BV_{CEO} > -100V$
- Maximum continuous current  $I_C = -1A$
- $h_{FE} > 100$  @  $I_C = -150mA$ ,  $V_{CE} = -0.2V$
- **Lead Free, RoHS Compliant (Note 1)**
- **Halogen and Antimony Free "Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

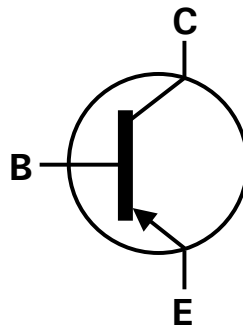
**Applications**

- LED TV backlight

**Mechanical Data**

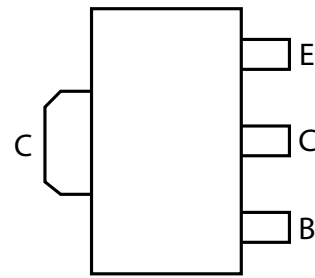
- Case: SOT89
- Case material: molded Plastic. "Green" molding Compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.052 grams (Approximate)

SOT89



Top View

Device Symbol



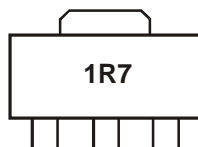
Top View  
Pin-Out

**Ordering Information** (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP4003ZTA	1R7	7	12	1000 units

- Notes:
1. No purposefully added lead.
  2. "Green" devices, Halogen and Antimony Free, Diodes Inc's "Green" Policy can be found on our website at <http://www.diodes.com>
  3. For Packaging Details, go to our website at <http://www.diodes.com>.

**Marking Information**



1R7 = Product type Marking Code

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

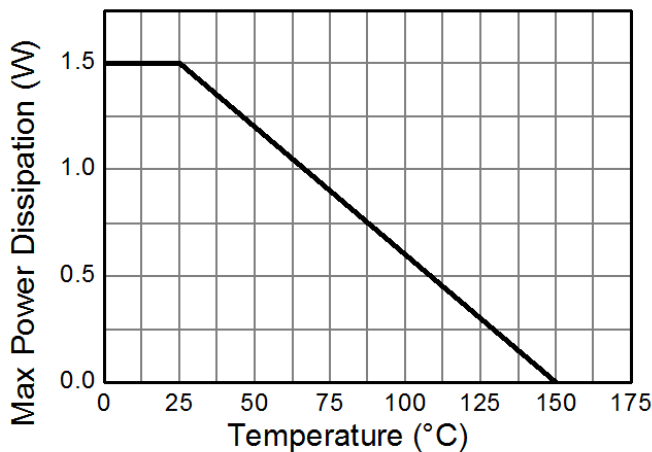
Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-1	A
Peak Pulse Current (Note 4)	I <sub>CM</sub>	-3	A
Base Current	I <sub>B</sub>	-500	mA

**Thermal Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

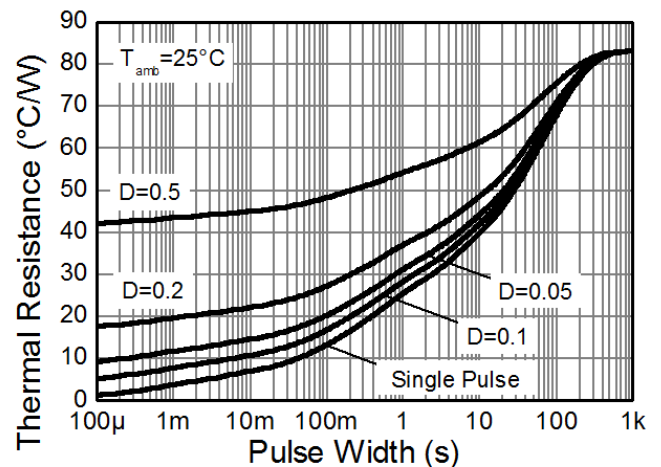
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	83	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R <sub>θJL</sub>	17.46	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

- Notes:
4. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.
  5. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions
  6. Thermal resistance from junction to solder-point (on the exposed collector pad).

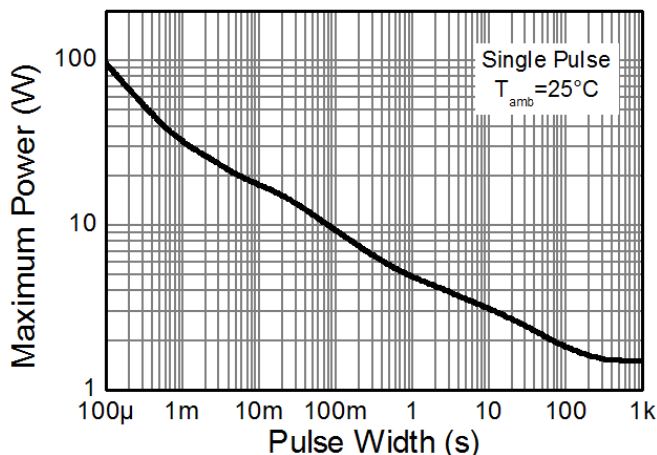
**Thermal Characteristics and Derating Information**



**Derating Curve**



**Transient Thermal Impedance**



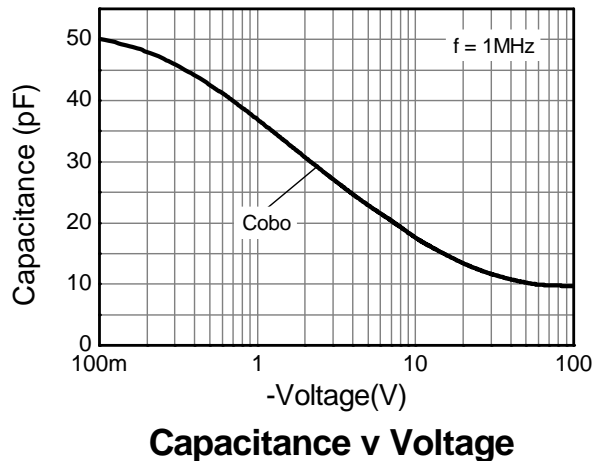
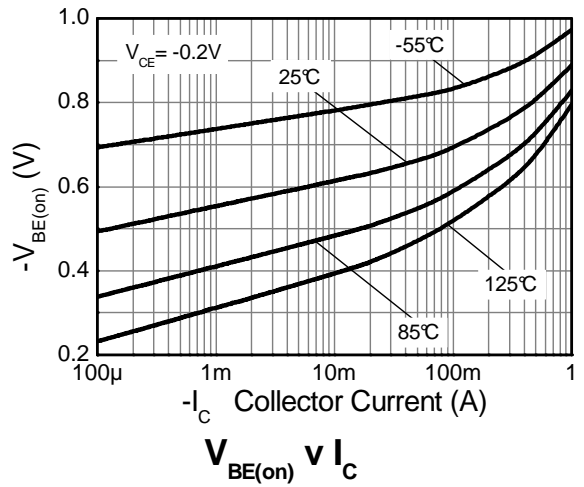
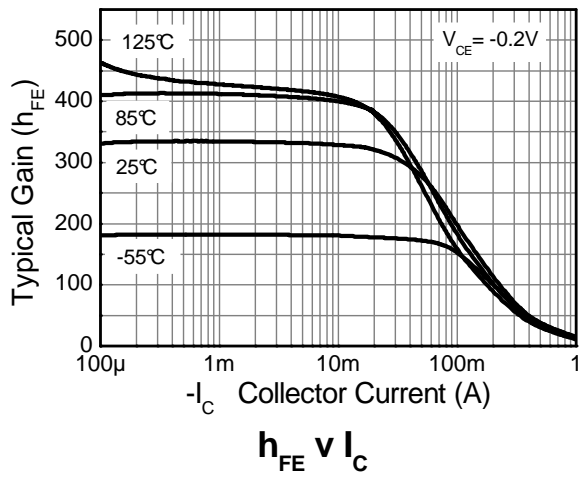
**Pulse Power Dissipation**

**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

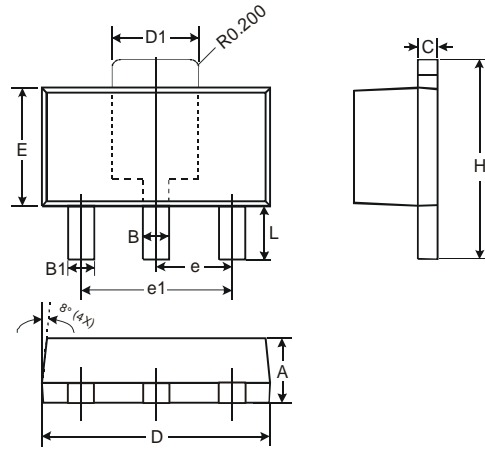
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Emitter Breakdown Voltage (Note 7)	$BV_{CEO}$	-100	-170	-	V	$I_C = -10\text{mA}$
Collector Cut-off Current	$I_{CBO}$	-	-	-50	nA	$V_{CB} = -100\text{V}$
Emitter Cut-off Current	$I_{EBO}$	-	-	-50	nA	$V_{EB} = -7\text{V}$
Static Forward Current Transfer Ratio (Note 7)	$h_{FE}$	60 100	133 112	-	-	$I_C = -85\text{mA}, V_{CE} = -0.15\text{V}$ $I_C = -150\text{mA}, V_{CE} = -0.2\text{V}$
Base-Emitter Turn-On Voltage (Note 7)	$V_{BE(on)}$	-	-0.71	-0.95	V	$I_C = -150\text{mA}, V_{CE} = -0.2\text{V}$
Delay Time	$t_{(d)}$	-	378	-	ns	$V_{CC} = -80\text{V}, I_C = -150\text{mA}, f$ $-I_{B2} = 1.5\text{mA}, V_{CE(ON)} = -0.2\text{V}$
Rise Time	$t_{(r)}$	-	388	-	ns	
Storage Time	$t_{(s)}$	-	1348	-	ns	
Fall Time	$t_{(f)}$	-	382	-	ns	$V_{CC} = -80\text{V}, I_C = -150\text{mA},$ $-I_{B2} = -1.5\text{mA}, V_{CE(ON)} = -4\text{V}$
Storage Time	$t_{(s)}$	-	75	-	ns	
Fall Time	$t_{(f)}$	-	363	-	ns	

Notes: 7. Measured under pulsed conditions. Pulse width = 300 $\mu\text{s}$ . Duty cycle  $\leq 2\%$

**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

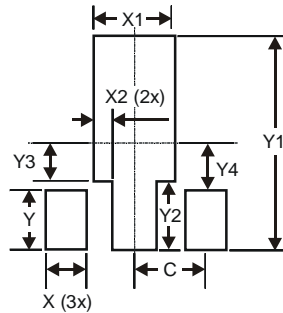


**Package Outline Dimensions**



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.43
D	4.40	4.60
D1	1.52	1.83
E	2.29	2.60
e	1.50 Typ	
e1	3.00 Typ	
H	3.94	4.25
L	0.89	1.20
All Dimensions in mm		

**Suggested Pad Layout**



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

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